

Thyristor

MCO75-12io1

V_{RRM}	=	1200 V
I _{tav}	=	80 A
V _T	=	1.27 V

Single Thyristor

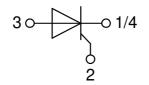
Part number

MCO75-12io1



Backside: isolated





Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper
- internally DCB isolated
- Advanced power cycling

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MCO75-12io1

Thyristo	r				Ratings	5	1
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM/DSM}	max. non-repetitive reverse/forwa	ard blocking voltage	$T_{VJ} = 25^{\circ}C$			1300	V
V _{RRM/DRM}	max. repetitive reverse/forward b	locking voltage	$T_{VJ} = 25^{\circ}C$			1200	V
I _{R/D}	reverse current, drain current	V _{R/D} = 1200 V	$T_{vJ} = 25^{\circ}C$			50	μA
		V _{R/D} = 1200 V	$T_{VJ} = 125^{\circ}C$			10	mA
V _T	forward voltage drop	$I_{T} = 75 A$	$T_{vJ} = 25^{\circ}C$			1.28	V
		$I_{T} = 150 \text{ A}$				1.60	V
		$I_{T} = 75 A$	$T_{vJ} = 125 \degree C$			1.27	V
		I _T = 150 A				1.67	V
ITAV	average forward current	$T_c = 80^{\circ}C$	$T_{vJ} = 150 ^{\circ}C$			80	A
I _{T(RMS)}	RMS forward current	180° sine				125	A
V _{T0}	threshold voltage	oss calculation only	$T_{vJ} = 150^{\circ}C$			0.85	V
r _T	slope resistance	oss calculation only				5.5	mΩ
R _{thJC}	thermal resistance junction to cas	se				0.45	K/W
R _{thCH}	thermal resistance case to heatsi	ink			0.1		K/W
P _{tot}	total power dissipation		$T_c = 25^{\circ}C$			270	W
I _{TSM}	max. forward surge current	t = 10 ms; (50 Hz), sine	$T_{vJ} = 45^{\circ}C$			1.07	kA
		t = 8,3 ms; (60 Hz), sine	$V_{R} = 0 V$			1.16	kA
		t = 10 ms; (50 Hz), sine	$T_{vJ} = 150$ °C			910	Α
		t = 8,3 ms; (60 Hz), sine	$V_{R} = 0 V$			980	А
l²t	value for fusing	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			5.73	kA²s
		t = 8,3 ms; (60 Hz), sine	$V_{R} = 0 V$			5.55	kA²s
		t = 10 ms; (50 Hz), sine	$T_{vJ} = 150^{\circ}C$			4.14	kA²s
		t = 8,3 ms; (60 Hz), sine	$V_{R} = 0 V$			4.00	kA²s
CJ	junction capacitance	$V_{R} = 400 V f = 1 MHz$	$T_{vJ} = 25^{\circ}C$		54		pF
P _{GM}	max. gate power dissipation	t _P = 30 μs	$T_c = 150^{\circ}C$			10	W
		t _P = 300 μs				5	W
P _{GAV}	average gate power dissipation					0.5	W
(di/dt) _{cr}	critical rate of rise of current	T _{vJ} = 150 °C; f = 50 Hz re	petitive, $I_{T} = 225 \text{ A}$			150	A/µs
		$I_{G} = 0.3 \text{ A}; \text{ V} = \frac{2}{3} \text{ V}_{DRM}$ nc	on-repet., $I_{\tau} = 75 \text{ A}$			500	A/µs
(dv/dt) _{cr}	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{vJ} = 150^{\circ}C$			1000	V/µs
		R _{GK} = ∞; method 1 (linear voltag	ge rise)				
V _{GT}	gate trigger voltage	$V_{\rm D} = 6 \text{ V}$	$T_{VJ} = 25^{\circ}C$			1.5	V
			$T_{vJ} = -40^{\circ}C$			1.6	V
I _{GT}	gate trigger current	$V_{D} = 6 V$	$T_{vJ} = 25^{\circ}C$			100	mA
			$T_{vJ} = -40^{\circ}C$			200	mA
V _{gd}	gate non-trigger voltage	$V_{D} = \frac{2}{3} V_{DBM}$	T _{v.l} = 150°C			0.2	V
	gate non-trigger current	2 2				10	mA
	latching current	t _p = 10 μs	$T_{vJ} = 25 °C$			450	mA
-	-	$I_{\rm G} = 0.3 \text{A}; \text{di}_{\rm G}/\text{dt} = 0.3 \text{A}/\mu\text{s}$					
I _H	holding current	$V_{\rm D} = 6 \ V \ R_{\rm GK} = \infty$	$T_{vJ} = 25 ^{\circ}C$			200	mA
t _{gd}	gate controlled delay time	$V_{\rm D} = \frac{1}{2} V_{\rm DRM}$	$T_{\rm VJ} = 25^{\circ}\rm C$			2	μs
- yu		$I_{\rm G} = 0.3 \text{A}; \text{di}_{\rm G}/\text{dt} = 0.3 \text{A}/\mu\text{s}$				_	
t _q	turn-off time	$V_{\rm B} = 100 \text{ V}; \ I_{\rm T} = 75\text{A}; \text{V} = \frac{2}{3}$			150		μs
- q	-	$di/dt = 10 \text{ A}/\mu \text{s} dv/dt = 15 \text{ V}/\mu \text{s}$					وم
		$u_{1}u_{1} = 10 A_{1}\mu_{3} u_{1}u_{1} = 15 V/$	$\mu_{p} = 200 \mu_{s}$				<u> </u>

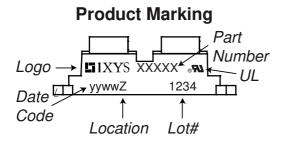
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Package	Package SOT-227B (minibloc)			Ratings				
Symbol	Definition	Conditions			min.	typ.	max.	Unit
	RMS current	per terminal "					150	А
\mathbf{T}_{v_J}	virtual junction temperature				-40		150	°C
T _{op}	operation temperature				-40		125	°C
T _{stg}	storage temperature						150	°C
Weight						30		g
M _D	mounting torque				1.1		1.5	Nm
M _T	terminal torque				1.1		1.5	Nm
d _{Spp/App}			terminal to terminal	10.5	3.2			mm
d _{Spb/Apb}	creepage distance on suna	ge distance on surface striking distance through air		8.6	6.8			mm
V	isolation voltage	t = 1 second			3000			V
	t = 1 minute		50/60 Hz, RMS; liso∟ ≤ 1 mA		2500			V

¹⁾ I_{must} is typically limited by the pin-to-chip resistance (1); or by the current capability of the chip (2). In case of (1) and a product with multiple pins for one chip-potential, the current capability can be increased by connecting the pins as one contact.



[Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
	Standard	MCO75-12io1	MCO75-12io1	Tube	10	505515

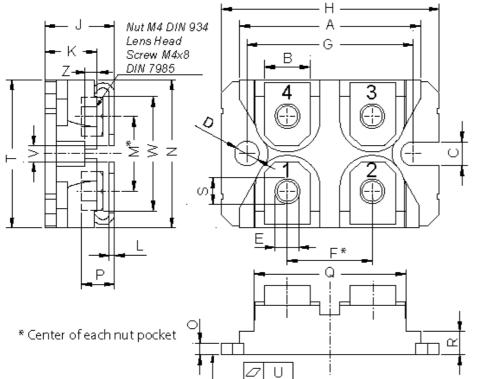
Equiva	lent Circuits for	Simulation	* on die level	$T_{VJ} = 150^{\circ}C$
)[R]-	Thyristor		
V _{0 max}	threshold voltage	0.85		V
$\mathbf{R}_{0 \max}$	slope resistance *	3.4		mΩ

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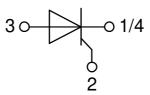
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Outlines SOT-227B (minibloc)



Dim.	Millir	neter	Inc	hes
Dim.	min	max	min	max
Α	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
С	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
Н	37.80	38.23	1.488	1.505
J	11.68	12.22	0.460	0.481
К	8.92	9.60	0.351	0.378
L	0.74	0.84	0.029	0.033
Μ	12.50	13.10	0.492	0.516
Ν	25.15	25.42	0.990	1.001
0	1.95	2.13	0.077	0.084
Ρ	4.95	6.20	0.195	0.244
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.167
S	4.55	4.85	0.179	0.191
Т	24.59	25.25	0.968	0.994
U	-0.05	0.10	-0.002	0.004
V	3.20	5.50	0.126	0.217
W	19.81	21.08	0.780	0.830
Ζ	2.50	2.70	0.098	0.106



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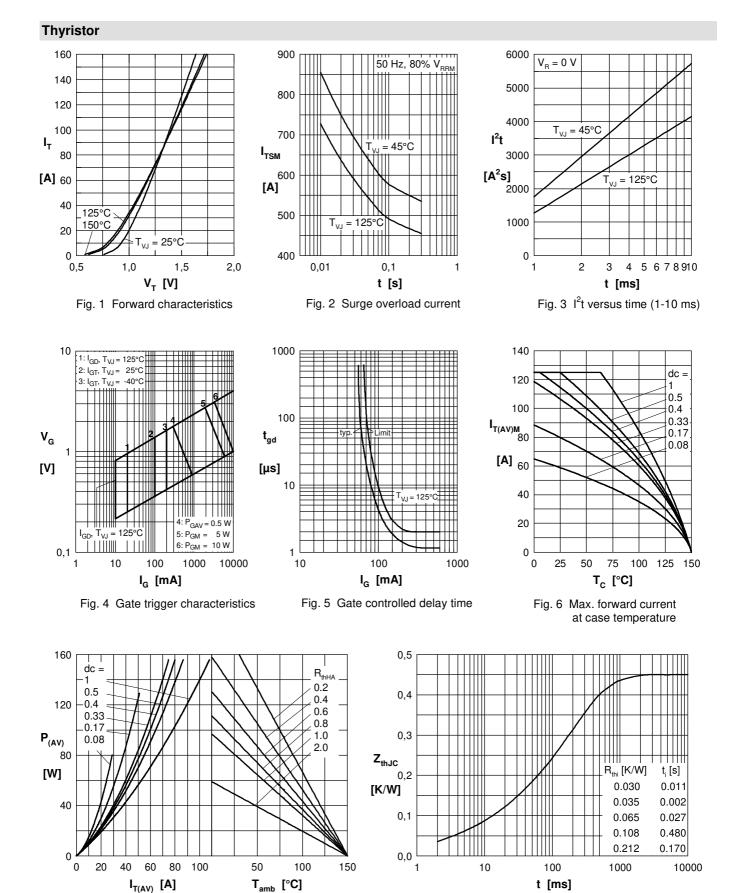


Fig. 7a Power dissipation versus direct output current Fig. 7b and ambient temperature

Fig. 8 Transient thermal impedance junction to case

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25.640.5053.0						